



RECORDS OF REVISION			DOC. FIRST ISSUE
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1. Module Classification Information

W X 1 2 8 6 4 A-N Y G
 ① ② ③ ④ ⑤ ⑥ ⑦

① Brand : WINSTAR DISPLAY CORPORATION

② Display Type : H→Character Type, G→Graphic Type

③ Display Font : Graphic 128*64 Dots

④ Model serials no.

⑤ Backlight Type : N→Without backlight

B→EL, Blue green

A→LED, Amber

D→EL, Green

R→LED, Red

W→EL, White

O→LED, Orange

F→CCFL, White

G→LED, Green

Y→LED, Yellow Green

⑥ LCD Mode : B→TN Positive, Gray

T→FSTN Negative

N→TN Negative,

G→STN Positive, Gray

Y→STN Positive, Yellow Green

M→STN Negative, Blue

F→FSTN Positive

⑦ LCD Polarizer Type/ A→Reflective, N.T, 6:00

H→Transflective, W.T,6:00

Temperature range/ D→Reflective, N.T, 12:00

K→Transflective, W.T,12:00

View direction G→Reflective, W. T, 6:00

C→Transmissive, N.T,6:00

J→Reflective, W. T, 12:00

F→Transmissive, N.T,12:00

B→Transflective, N.T,6:00

I→Transmissive, W. T, 6:00

E→Transflective, N.T.12:00

L→Transmissive, W.T,12:00

⑧ Special Code

2. Precautions in use of LCD Modules

- (1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2) Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3) Don't disassemble the LCM.
- (4) Don't operate it above the absolute maximum rating.
- (5) Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.

3. General Specification

Item	Dimension	Unit
Number of Dots	128*64	
Module dimension(w/o TAB)	35.0x 24.22x 1.6(max)	mm
View area	29.58x 17.98	mm
Active area	25.58x 15.98	mm
Dot size	0.18x 0.23	mm
Dot pitch	0.20x 0.25	mm
LCD type	STN, positive, Reflective, Yellow Green	
Duty	1/64	
View direction	6 o'clock	

4. Absolute Maximum Ratings

Item	Symbol	Min	Typ	Max	Unit
Operating Temperature	T_{OP}	-20	—	+70	°C
Storage Temperature	T_{ST}	-30	—	+80	°C
Input Voltage	V_I	V_{SS}	—	V_{DD}	V
Supply Voltage For Logic	$V_{DD}-V_{SS}$	2.4	—	5.5	V
Supply Voltage For LCD	V_O-V_{SS}	4.0	—	15.0	V

5. Electrical Characteristics

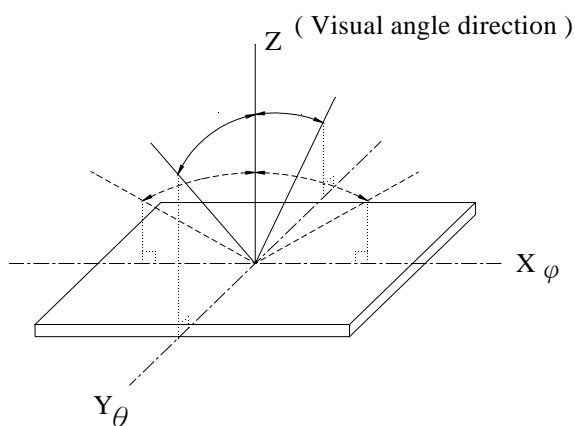
Item	Symbol	Condition	Min	Typ	Max	Unit
Supply Voltage For Logic	$V_{DD}-V_{SS}$	—	2.4	3.3	5.5	V
Supply Voltage For LCD	$V_{DD}-V_O$	$T_a=-20^{\circ}\text{C}$	—	—	10.5	V
		$T_a=25^{\circ}\text{C}$	—	8.2	—	V
		$T_a=70^{\circ}\text{C}$	6.8	—	—	V
Input High Volt.	V_{IH}	—	$0.8 V_{DD}$	—	V_{DD}	V
Input Low Volt.	V_{IL}	—	—	—	$0.2 V_{DD}$	V
Output High Volt.	V_{OH}	—	$0.8 V_{DD}$	—	—	V
Output Low Volt.	V_{OL}	—	—	—	$0.2 V_{DD}$	V
Supply Current	I_{DD}	$V_{DD}=3.3\text{V}$	0.5	0.8	1.0	mA

6. Optical Characteristics

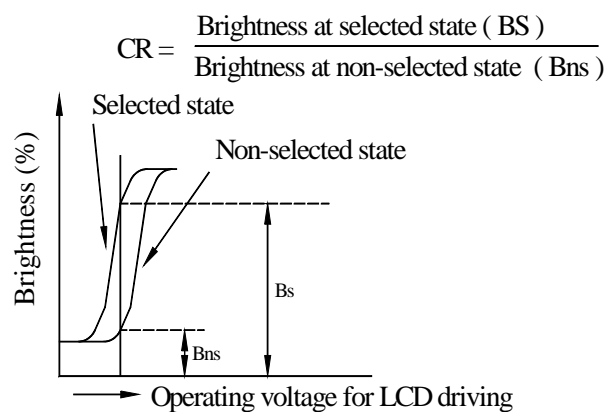
Item	Symbol	Condition	Min	Typ	Max	Unit
View Angle	(V) θ	$CR \geq 2$	20	—	40	deg
	(H) φ	$CR \geq 2$	-30	—	30	deg
Contrast Ratio	CR	—	—	3	—	—
Response Time	T rise	—	—	110	220	ms
	T fall	—	—	260	520	ms

6.1 Definitions

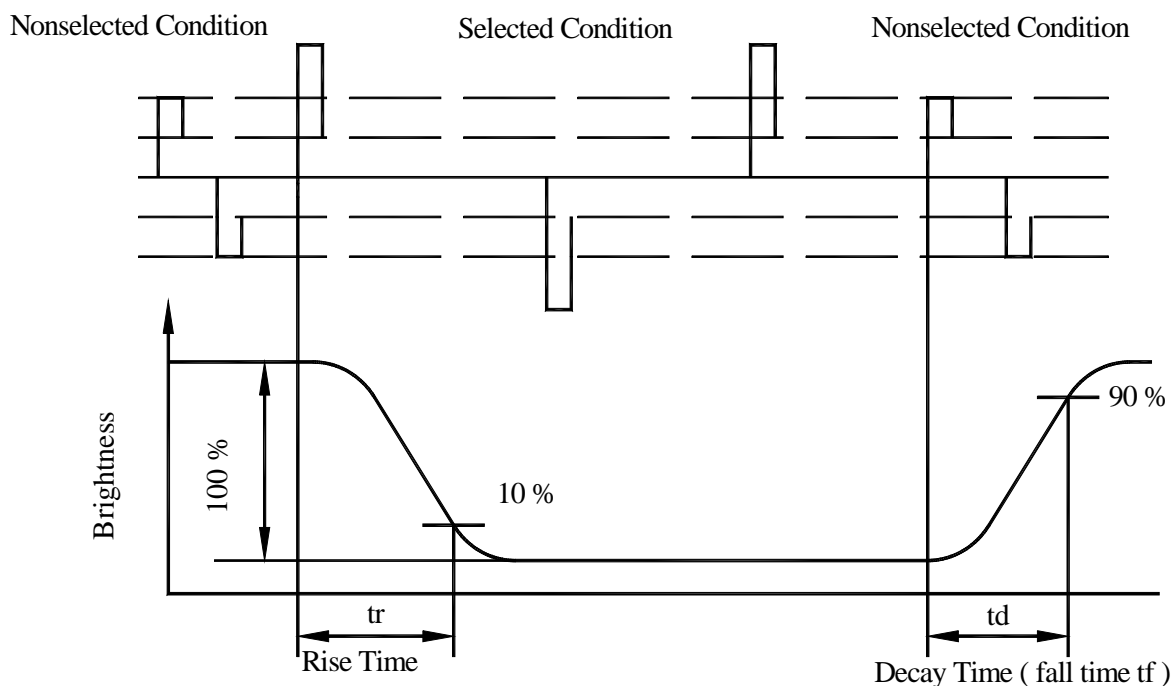
View Angles



Contrast Ratio



Response Time



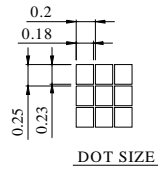
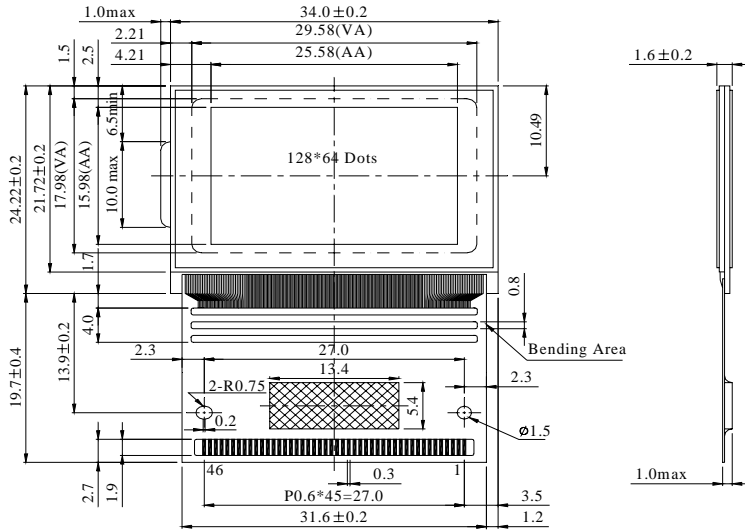
7. Interface Description

Pin No.	Symbol	I/O	Description
1	NC	—	No connection
2	TEMPS	I	Selects temperature coefficient of the reference voltage TEMPS="L": -0.05% °C, TEMPS="H": -0.2% °C
3	INTRS	I	Internal resistors select pin This pin selects the resistors for adjusting V0 voltage level. INTRS="H": use the internal resistor. INTRS="L": use the external resistor. V0 voltage is controlled with VR pin and external resistive divider.
4	HPM	I	Power control pin of the power supply circuit for LCD driver. HPM="H": high power mode HPM="L": normal power mode This pin is valid in master operation.
5	DCDC5B	I	5times boosting circuit enable input pin. When this pin is low in 4 times boosting circuit, the 5-time boosting voltage appears at VOUT.
6	BSTS	I	Select input voltage of the built-in voltage converter. Voltage converter input BSTS="H": 4V (VDD>4V) BSTS="L": VDD (2.4V ≤ VDD ≤ 5.5V) When BSTS pin is "L", VDD must be higher than 4V in our 4-time boosting.
7~11	V0~V4	I/O	LCD driver supply voltages. The voltage determined by LCD pixel is impedance-converted by an operational amplifier for application. Voltages should have the following relational; $V0 \geq V1 \geq V2 \geq V3 \geq V4 \geq VSS$
12	VR	I	V0 voltage adjustment pin. It is valid only when on-chip resistors are not used(INTRS="L")
13	C2-	O	Capacitor 2 negative connection pin for voltage converter.
14	C2+	O	Capacitor 2 positive connection pin for voltage converter.
15	C1-	O	Capacitor 1 negative connection pin for voltage converter.
16	C1+	O	Capacitor 1 positive connection pin for voltage converter.
17	C3-	O	Capacitor 1 negative connection pin for voltage converter.
18	C3+	O	Capacitor 1 positive connection pin for voltage converter.
19	VOUT	I/O	Voltage converter input/output pin.
20	VDD	—	Power supply pin for logic.
21	VSS	—	Ground pin, connected to 0V

22	PS	I	Parallel/Serial data input select pin. Interface Data Read/Write Serial clock PS="H": Parallel DB0~DB7 E_RD,RW_WR - PS="L": Serial SID(DB7) Write only SCLK(DB6) In serial mode, it is impossible to read data from the on-chip RAM. And DB0 to DB5 are high impedance and E_RD and RW_WR must be fixed to either "H" or "L".												
23	MI	I	Microprocessor interface selects pin. MI="H": 6800-series MPU interface MI="L": 8080-series MPU interface												
24	CLS	I	Built-in oscillator circuit enable/disable select pin. CLS="H": enable CLS="L": disable(external display clock input from CL pin)												
25	MS	I	Master or Slave mode operation select pin. MS="H" : master operation MS="L" : slave operation												
26 27	DUTY1 DUTY0	I	The LCD driver duty ratio depends on the following table <table border="1" style="margin-left: auto; margin-right: auto;"> <thead> <tr> <th>DUTY1</th> <th>DUTY0</th> <th>Duty ratio</th> </tr> </thead> <tbody> <tr> <td>L</td> <td>L</td> <td>1/33</td> </tr> <tr> <td>L</td> <td>H</td> <td>1/49</td> </tr> <tr> <td>H</td> <td>L</td> <td>1/65</td> </tr> </tbody> </table>	DUTY1	DUTY0	Duty ratio	L	L	1/33	L	H	1/49	H	L	1/65
DUTY1	DUTY0	Duty ratio													
L	L	1/33													
L	H	1/49													
H	L	1/65													
28~35	DB7~DB0	I/O	8-bit bi-directional data bus that is connected to the standard 8-bit microprocessor data bus. When the serial interface selected(PS="L") DB0~DB5: high impedance DB6: serial input clock (SCLK) DB7: serial input data (SID) When chip select is not active, DB0~DB7 may be high impedance.												
36	E_RD	I	When connected to 80-family MPU: Read enable clock input pin. When /RD is "L", DB0~DB7 are in an output status When connected to 68-family MPU: RW = "H": When E is "H", DB0~DB7 are in an output status RW = "L": The data on DB0~DB7 are latched at the falling edge of the E signal												
37	RW_WR	I	When connected to 80-family MPU: Write enable clock input pin. The data ON DB0~DB7 are latched at the rising edge of the /WR signal. When connected to 68-family MPU: RW = "H": read RW = "L": write												
38	RS	I	Register select pin RS="H": DB0~DB7 are display data RS="L": DB0~DB7 are control data												
39	RESETB	I	Reset input pin When RESETB is "L", initialization is executed.												
40 41	CS2 CS1B	I	Chip select input pins Data/instruction I/O enable only when CS1B is "L" and CS2 is "H". When chip select is non-active, DB0~DB7 may be high impedance.												
42	DISP	I/O	LCD display blanking control input /output When KS0713 is used in master/slave mode (multi-chip), the DISP pins must be connected each other. MS="H": output MS="L": input												

43	CL	I/O	Display clock input/output pin When the KS0713 is used in master/slave mode (multi-chip), the CL pins must be connected each other.
44	M	I/O	LCD AC signal input /output pin When KS0713 is used in master/slave mode (multi-chip), the M pins must be connected each other. MS="H": output MS="L": input
45	FRS	O	Static driver segment output pin This pin is used together with the M pin.
46	NC	—	No connection.

8. Contour Drawing & Block Diagram



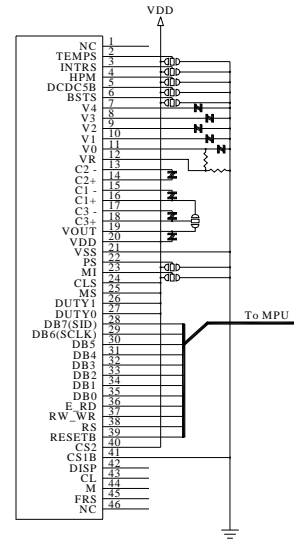
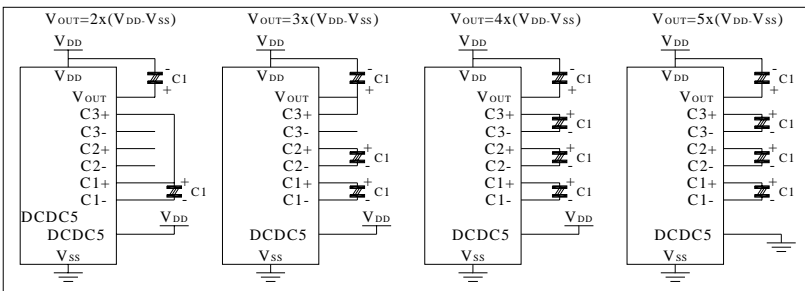
PIN NO.	SYMBOL	DISP	CL	M	FRS	NC	21	V _{SS}	22	PS	23	MI	24	CLS	3	INTRS	25	MS	4	HPM	26	DUTY1	5	DCDC5B	27	DUTY0	6	BSTS	28	DB7	7	V4	29	DB6	8	V3	30	DB5	9	V2	31	DB4	10	V1	32	DB3	11	V0	33	DB2	12	VR	34	DB1	13	C2-	35	DB0	14	C2+	36	E_RD	15	C1-	37	RW_WR	16	C1+	38	RS	17	C3-	39	RESETB	18	C3+	40	CS2	19	Vout	41	CS1B	20	Vdd
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The non-specified tolerance of diemnsion is ±0.15mm.

Display Data RAM

Page Address P3,P2,P1,P0	Data	RAM address	Line Address (HEX)	Com Output
0,0,0,0	DB0	[RAM Address Grid]	00	COM1
	DB1		01	COM2
	DB2		02	COM3
	DB3		03	COM4
	DB4		04	COM5
	DB5		05	COM6
	DB6		06	COM7
	DB7		07	COM8
?			?	?
0,1,1,1	DB0	[RAM Address Grid]	38	COM57
	DB1		39	COM58
	DB2		3A	COM59
	DB3		3B	COM60
	DB4		3C	COM61
	DB5		3D	COM62
	DB6		3E	COM63
	DB7		3F	COM64
0,1,1,1	DB0		40	COM65
Column Address	ADC=0	83 82 81 80 7F 7E 7D 7C 7B 7A	~ ~ ~	5 4 3 2 1 0
Address	ADC=1	0 1 2 3 4 5 6 7 8 9	7E 7F 80 81 82 83	
Segment Output		132 131 130 129 128 127 126 125 124 123	~ ~ ~	6 5 4 3 2 1

Boosting Circuit



Application Circuit

9. Fuction Description

Chip Select Input

There are CS1B and CS2 pins for Chip Selection. The KS0713 can interface with an MPU only when CS1B is "L" and CS2 is "H". When these pins are set to any other combination, RS, E_RD, and RW_WR inputs are disabled and DB0 to DB7 are to be high impedance. And, in case of serial interface, the internal shift register and the counter are reset.

Parallel / Serial Interface

KS0713 has three types of interface with an MPU, which are one serial and two parallel interfaces. This parallel or serial interface is determined by PS pin as shown in table 8.

Table 8. Parallel / Serial Interface Mode

PS	Type	CS1B	CS2	MI	Interface mode
H	Parallel	CS1B	CS2	H	6800-series MPU mode
				L	8080-series MPU mode
L	Serial	CS1B	CS2	*x	Serial-mode

*x : Don't care

Parallel Interface (PS = "H")

The 8-bit bi-directional data bus is used in parallel interface and the type of MPU is selected by MI as shown in table 9. The type of data transfer is determined by signals at RS, E_RD and RW_WR as shown in table10.

Table 9. Microprocessor Selection for Parallel Interface

MI	CS1B	CS2	RS	E_RD	RW_WR	DB0 to DB7	MPU bus
H	CS1B	CS2	RS	E	RW	DB0 to DB7	6800-series
L	CS1B	CS2	RS	/RD	/WR	DB0 to DB7	8080-series

Table 10. Parallel Data Transfer

Common	6800-series		8080-series		Description
	E_RD (E)	RW_WR (RW)	E_RD (/RD)	RW_WR (/WR)	
RS					
H	H	H	L	H	Display data read out
H	H	L	H	L	Display data write
L	H	H	L	H	Register status read
L	H	L	H	L	Writes to internal register (instruction)

Serial Interface (PS = "L")

When the KS0713 is active, serial data (DB7) and serial clock (DB6) inputs are enabled. And not active, the internal 8-bit shift register and the 3-bit counter are reset. Serial data can be read on the rising edge of serial clock going into DB6 and processed as 8-bit parallel data on the eighth serial clock. Serial data input is display data when RS is high and control data when RS is low. Since the clock signal (DB6) is easy to be affected by the external noise caused by the line length, the operation check on the actual machine is recommended.

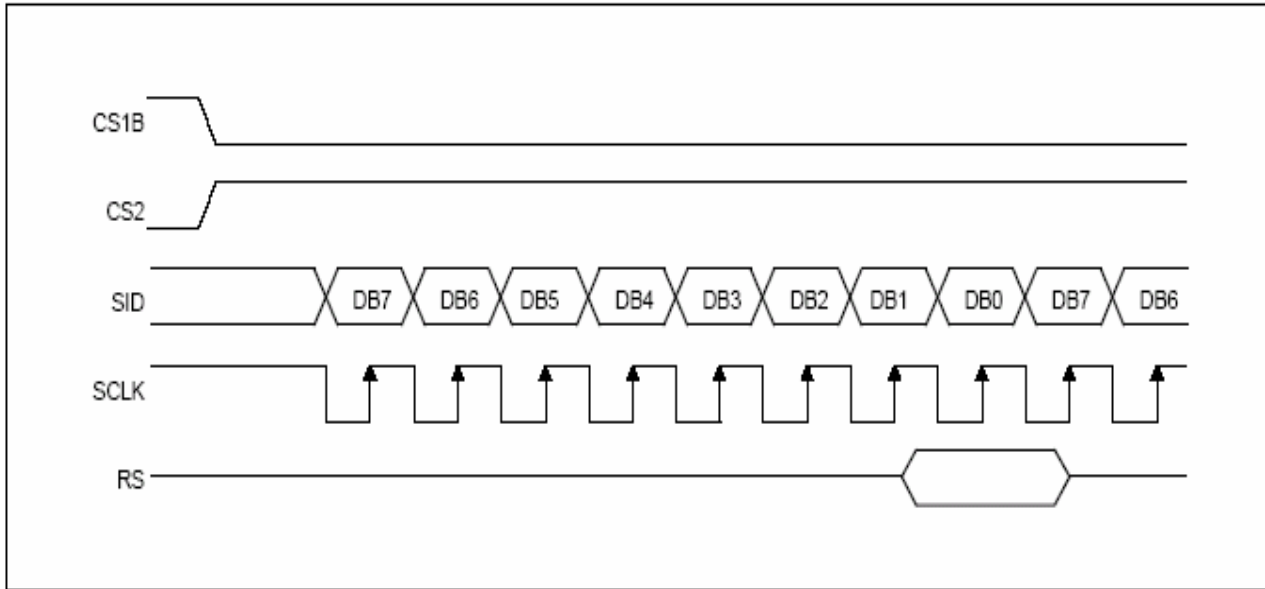


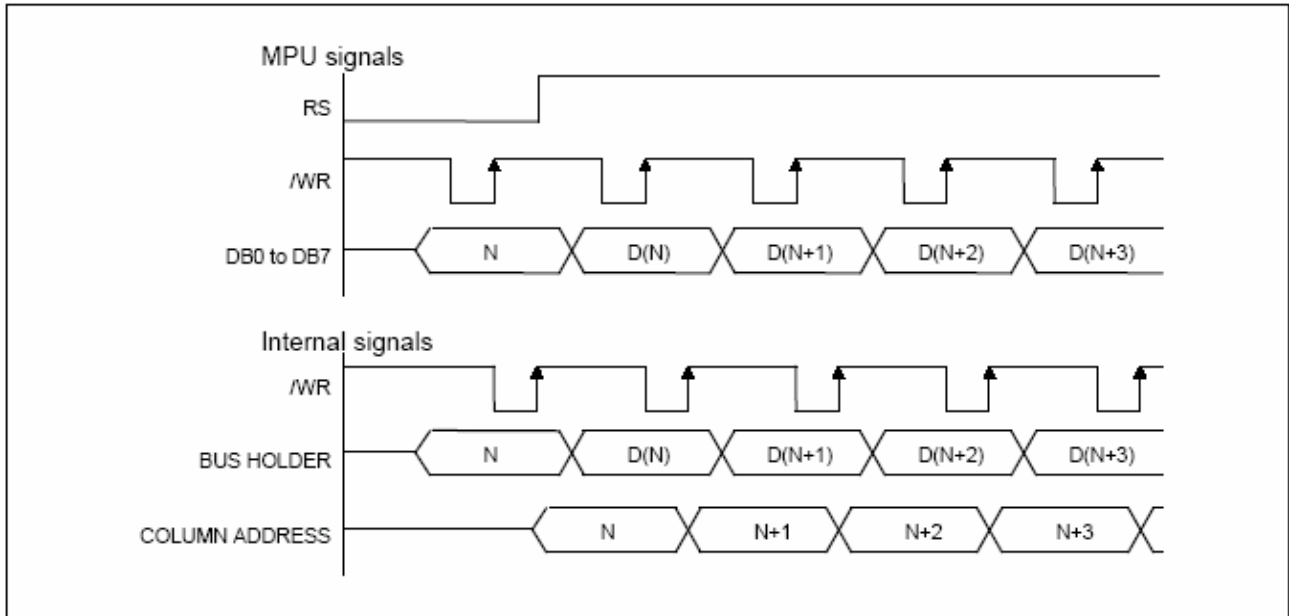
Figure 3. Serial Interface Timing

Busy Flag

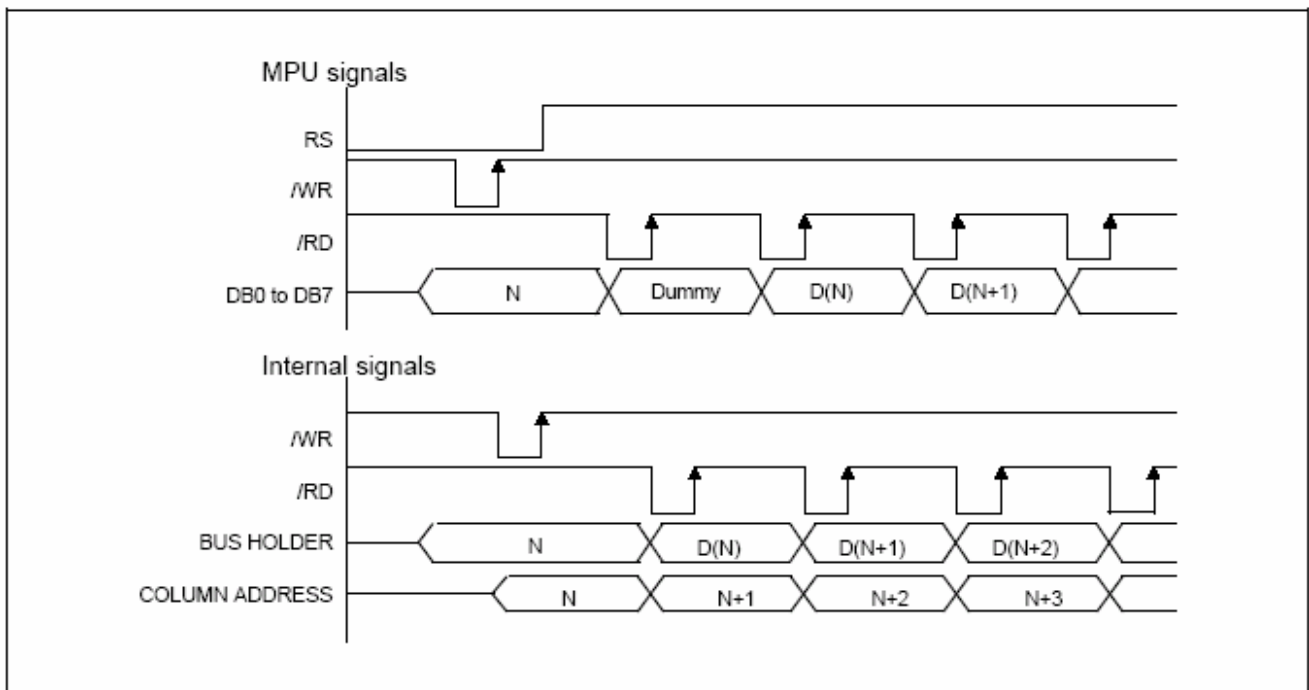
The Busy Flag indicates whether the KS0713 is operating or not. When DB7 is "H" in read status operation, this device is in busy status and will accept only read status instruction. If the cycle time is correct, the microprocessor needs not to check this flag before each instruction, which improves the MPU performance.

Data Transfer

The KS0713 uses bus holder and internal data bus for Data Transfer with the MPU. When writing data from the MPU to on-chip RAM, data is automatically transferred from the bus holder to the RAM as shown in figure 4. And when reading data from on-chip RAM to the MPU, the data for the initial read cycle is stored in the bus holder (dummy read) and the MPU reads this stored data from bus holder for the next data read cycle as shown in figure 5. This means that a dummy read cycle must be inserted between each pair of address sets when a sequence of address sets is executed. Therefore, the data of the specified address cannot be output with the read display data instruction right after the address sets, but can be output at the second read of data.



Write Timing



Read Timing

10. Timing Characteristics

Read / Write Characteristics (8080-series MPU)

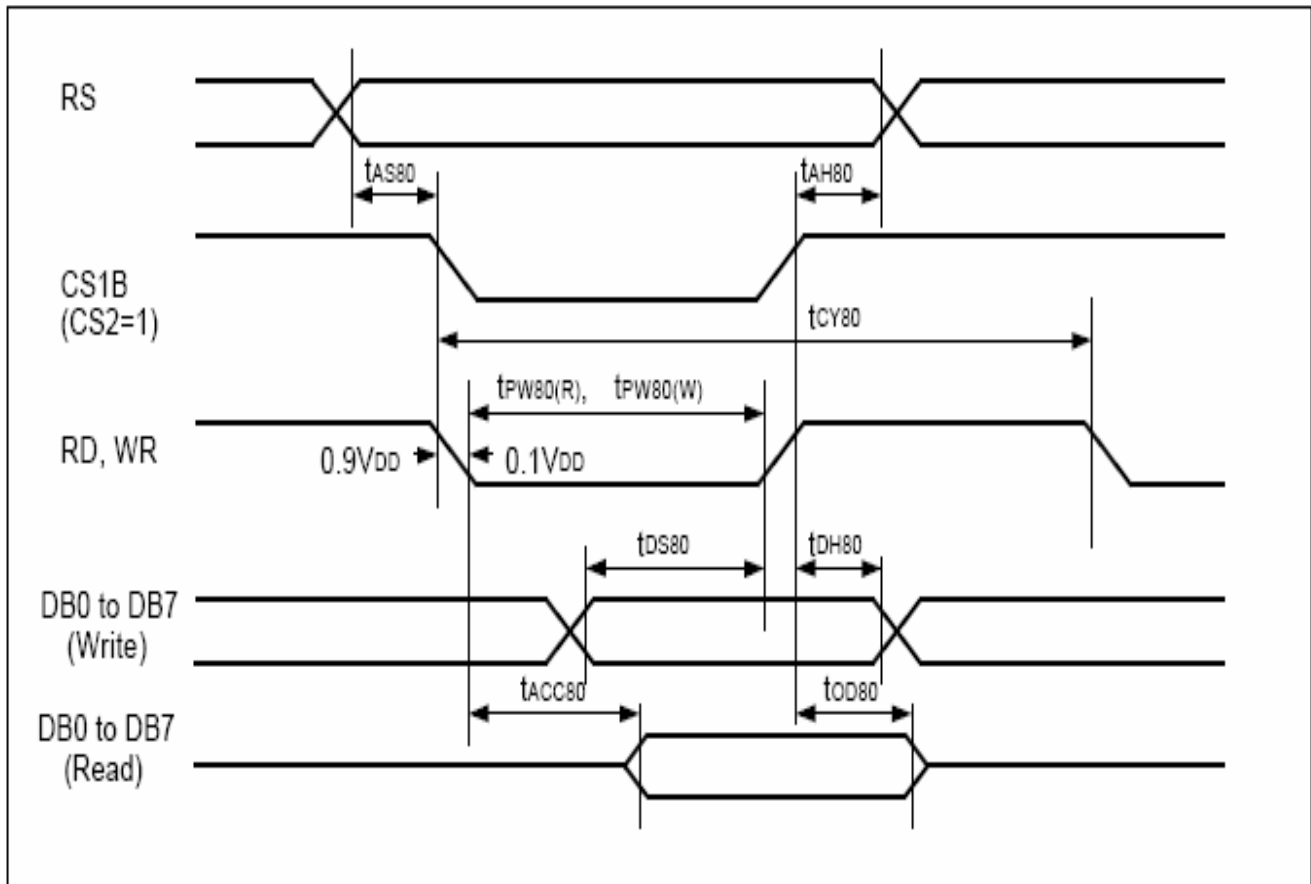


Figure 34. Read / Write Characteristics (8080-series MPU)

(V_{DD} = 2.4 to 3.6V, T_a = -40 to +85°C)

Item	Signal	Symbol	Min.	Typ.	Max.	Unit	Remark
Address setup time	RS	t _{AS80}	13	-	-	ns	
Address hold time	RS	t _{AH80}	17	-	-	ns	
System cycle time	RS	t _{CY80}	400	-	-	ns	
Pulse width (WR)	RW_WR	t _{PW80(W)}	55	-	-	ns	
Pulse width (RD)	E_RD	t _{PW80(R)}	125	-	-	ns	
Data setup time	DB7 to DB0	t _{DS80}	35	-	-	ns	
Data hold time		t _{DH80}	13	-	-	ns	
Read access time	DB0	t _{ACC80}	-	-	125	ns	C _L = 100 pF
Output disable time		t _{OD80}	10	-	90		

Read / Write Characteristics (6800-series Microprocessor)

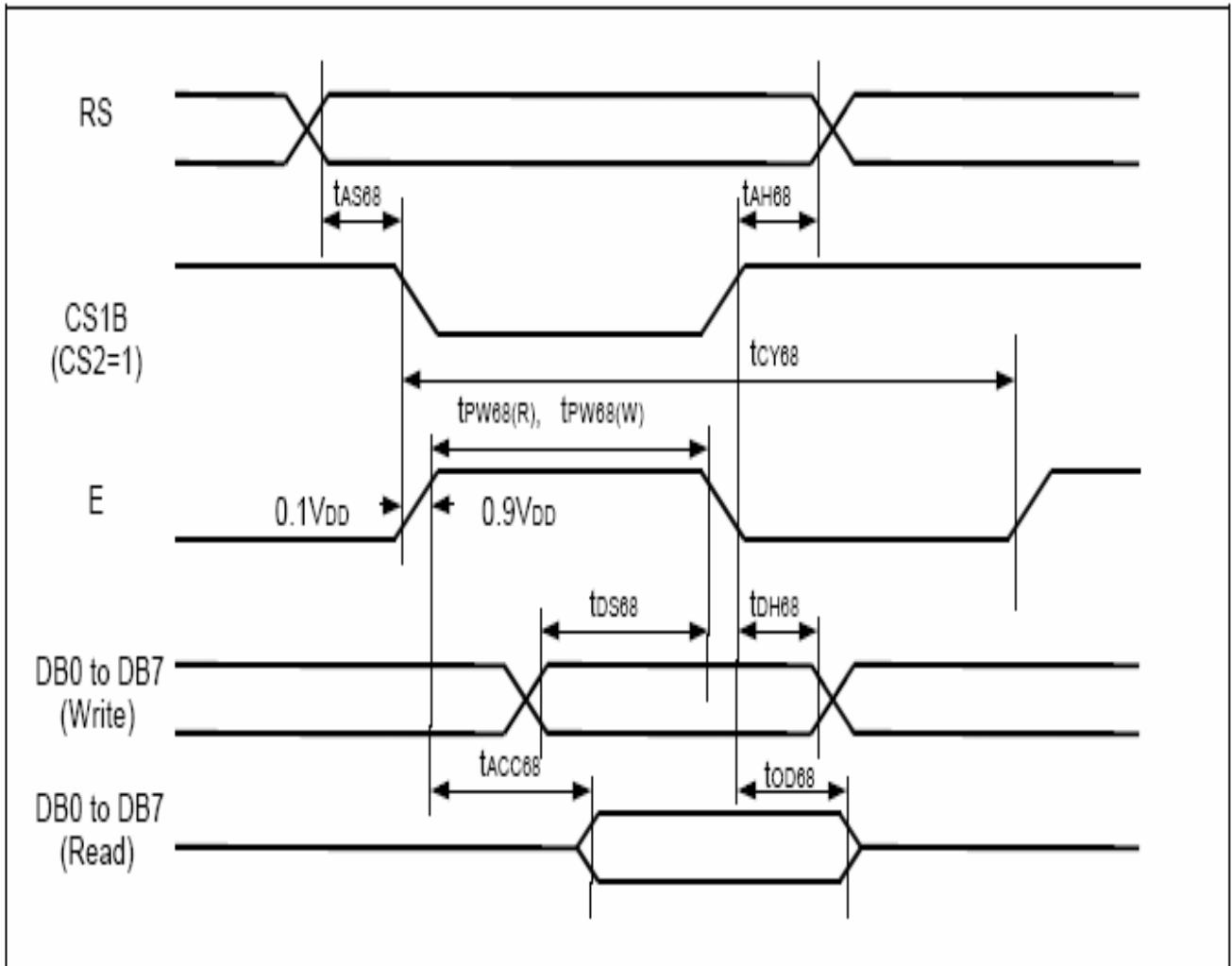


Figure 35. Read/Write Characteristics (6800-series Microprocessor)

(VDD = 2.4 to 3.6V, Ta = -40 to +85°C)

Item	Signal	Symbol	Min.	Typ.	Max.	Unit	Remark
Address setup time	RS	TAS68	13	-	-	ns	
Address hold time	RS	TAH68	17	-	-	ns	
System cycle time	RS	TCY68	400	-	-	ns	
Data setup time	DB7 to DB0	TDS68	35	-	-	ns	
Data hold time		TDH68	13	-	-	ns	
Access time	DB0	TACC68	-	-	125	ns	CL = 100 pF
Output disable time		TOD68	10	-	90		
Enable pulse width	Read write	E_RD	TPW68 (R)	125	-	-	
		E_RD	TPW68 (W)	55	-	-	

11. RELIABILITY

Content of Reliability Test (wide temperature, -20°C~70°C)

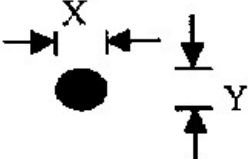
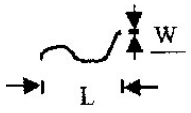
Environmental Test			
Test Item	Content of Test	Test Condition	Note
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2
Low Temperature storage	Endurance test applying the high storage temperature for a long time.	-30°C 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs	—
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1
High Temperature/ Humidity Operation	The module should be allowed to stand at 60 °C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation <div style="text-align: center;"> <p style="text-align: center;">-20°C 25°C 70°C</p> <p style="text-align: center;">30min 5min 30min</p> <p style="text-align: center;">1 cycle</p> </div>	-20°C/70°C 10 cycles	—
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude : 15mm Vibration Frequency : 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS=1.5kΩ CS=100pF 1 time	—

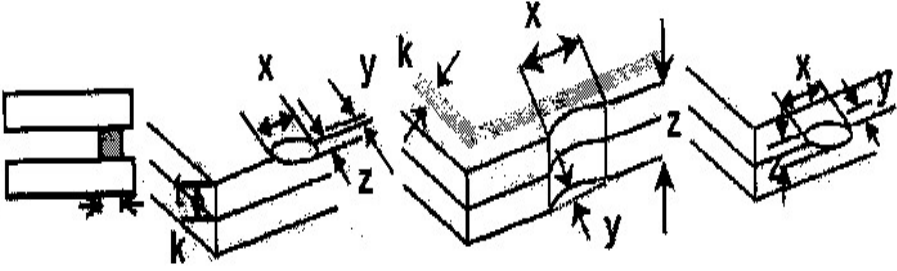
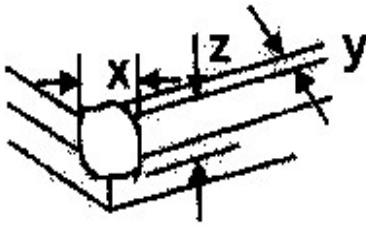
Note1: No dew condensation to be observed.

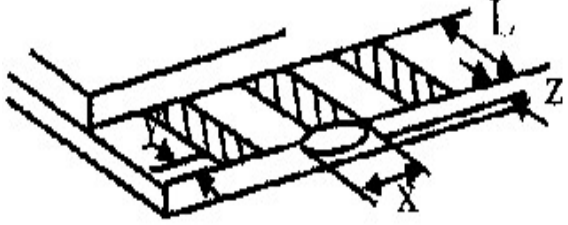
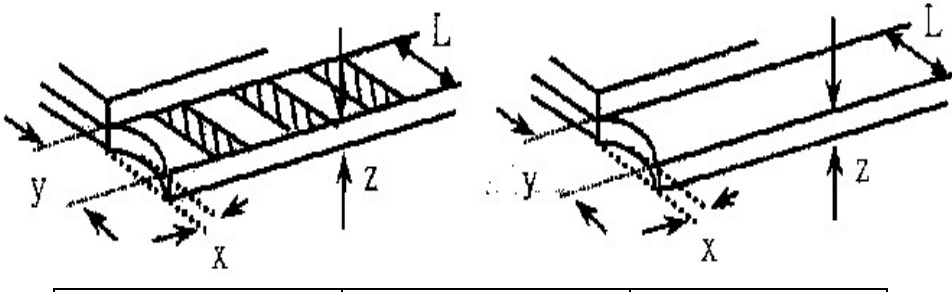
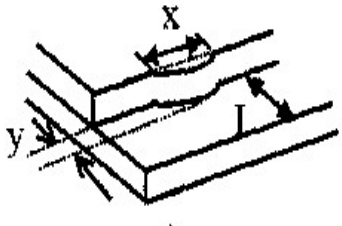
Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

Note3: Vibration test will be conducted to the product itself without putting it in a container.

12. Inspection specification

NO	Item	Criterion	AQL												
01	Electrical Testing	1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect.	0.65												
02	Black or white spots on LCD (display only)	2.1 White and black spots on display $\leq 0.25\text{mm}$, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm	2.5												
03	LCD black spots, white spots, contamination (non-display)	3.1 Round type : As following drawing $\Phi = (x + y) / 2$  <table border="1" data-bbox="874 967 1353 1182"> <thead> <tr> <th>SIZE</th> <th>Acceptable Q TY</th> </tr> </thead> <tbody> <tr> <td>$\Phi \leq 0.10$</td> <td>Accept no dense</td> </tr> <tr> <td>$0.10 < \Phi \leq 0.20$</td> <td>2</td> </tr> <tr> <td>$0.20 < \Phi \leq 0.25$</td> <td>1</td> </tr> <tr> <td>$0.25 < \Phi$</td> <td>0</td> </tr> </tbody> </table>	SIZE	Acceptable Q TY	$\Phi \leq 0.10$	Accept no dense	$0.10 < \Phi \leq 0.20$	2	$0.20 < \Phi \leq 0.25$	1	$0.25 < \Phi$	0	2.5		
		SIZE	Acceptable Q TY												
$\Phi \leq 0.10$	Accept no dense														
$0.10 < \Phi \leq 0.20$	2														
$0.20 < \Phi \leq 0.25$	1														
$0.25 < \Phi$	0														
3.2 Line type : (As following drawing)  <table border="1" data-bbox="705 1258 1353 1473"> <thead> <tr> <th>Length</th> <th>Width</th> <th>Acceptable Q TY</th> </tr> </thead> <tbody> <tr> <td>---</td> <td>$W \leq 0.02$</td> <td>Accept no dense</td> </tr> <tr> <td>$L \leq 3.0$</td> <td>$0.02 < W \leq 0.03$</td> <td rowspan="2">2</td> </tr> <tr> <td>$L \leq 2.5$</td> <td>$0.03 < W \leq 0.05$</td> </tr> <tr> <td>---</td> <td>$0.05 < W$</td> <td>As round type</td> </tr> </tbody> </table>	Length	Width	Acceptable Q TY	---	$W \leq 0.02$	Accept no dense	$L \leq 3.0$	$0.02 < W \leq 0.03$	2	$L \leq 2.5$	$0.03 < W \leq 0.05$	---	$0.05 < W$	As round type	2.5
Length	Width	Acceptable Q TY													
---	$W \leq 0.02$	Accept no dense													
$L \leq 3.0$	$0.02 < W \leq 0.03$	2													
$L \leq 2.5$	$0.03 < W \leq 0.05$														
---	$0.05 < W$	As round type													
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction. <table border="1" data-bbox="842 1523 1353 1771"> <thead> <tr> <th>Size Φ</th> <th>Acceptable Q TY</th> </tr> </thead> <tbody> <tr> <td>$\Phi \leq 0.20$</td> <td>Accept no dense</td> </tr> <tr> <td>$0.20 < \Phi \leq 0.50$</td> <td>3</td> </tr> <tr> <td>$0.50 < \Phi \leq 1.00$</td> <td>2</td> </tr> <tr> <td>$1.00 < \Phi$</td> <td>0</td> </tr> <tr> <td>Total Q TY</td> <td>3</td> </tr> </tbody> </table>	Size Φ	Acceptable Q TY	$\Phi \leq 0.20$	Accept no dense	$0.20 < \Phi \leq 0.50$	3	$0.50 < \Phi \leq 1.00$	2	$1.00 < \Phi$	0	Total Q TY	3	2.5
Size Φ	Acceptable Q TY														
$\Phi \leq 0.20$	Accept no dense														
$0.20 < \Phi \leq 0.50$	3														
$0.50 < \Phi \leq 1.00$	2														
$1.00 < \Phi$	0														
Total Q TY	3														

NO	Item	Criterion	AQL																		
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination																			
06	Chipped glass	<p>Symbols Define: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length:</p> <p>6.1 General glass chip : 6.1.1 Chip on panel surface and crack between panels:</p>  <table border="1" data-bbox="440 763 1353 893"> <thead> <tr> <th>z: Chip thickness</th> <th>y: Chip width</th> <th>x: Chip length</th> </tr> </thead> <tbody> <tr> <td>$Z \leq 1/2t$</td> <td>Not over viewing area</td> <td>$x \leq 1/8a$</td> </tr> <tr> <td>$1/2t < z \leq 2t$</td> <td>Not exceed 1/3k</td> <td>$x \leq 1/8a$</td> </tr> </tbody> </table> <p>⊙If there are 2 or more chips, x is total length of each chip.</p> <p>6.1.2 Corner crack:</p>  <table border="1" data-bbox="440 1285 1353 1415"> <thead> <tr> <th>z: Chip thickness</th> <th>y: Chip width</th> <th>x: Chip length</th> </tr> </thead> <tbody> <tr> <td>$Z \leq 1/2t$</td> <td>Not over viewing area</td> <td>$x \leq 1/8a$</td> </tr> <tr> <td>$1/2t < z \leq 2t$</td> <td>Not exceed 1/3k</td> <td>$x \leq 1/8a$</td> </tr> </tbody> </table> <p>⊙If there are 2 or more chips, x is the total length of each chip.</p>	z: Chip thickness	y: Chip width	x: Chip length	$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$	$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$	z: Chip thickness	y: Chip width	x: Chip length	$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$	$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$	2.5
z: Chip thickness	y: Chip width	x: Chip length																			
$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$																			
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z: Chip thickness	y: Chip width	x: Chip length																			
$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$																			
$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$																			

NO	Item	Criterion	AQL						
06	Glass crack	Symbols : x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 6.2 Protrusion over terminal : 6.2.1 Chip on electrode pad :	2.5						
									
		<table border="1" data-bbox="352 665 1265 750"> <tr> <td>y: Chip width</td> <td>x: Chip length</td> <td>z: Chip thickness</td> </tr> <tr> <td>$y \leq 0.5\text{mm}$</td> <td>$x \leq 1/8a$</td> <td>$0 < z \leq t$</td> </tr> </table>		y: Chip width	x: Chip length	z: Chip thickness	$y \leq 0.5\text{mm}$	$x \leq 1/8a$	$0 < z \leq t$
		y: Chip width		x: Chip length	z: Chip thickness				
$y \leq 0.5\text{mm}$	$x \leq 1/8a$	$0 < z \leq t$							
6.2.2 Non-conductive portion:									
									
<table border="1" data-bbox="426 1086 1265 1171"> <tr> <td>y: Chip width</td> <td>x: Chip length</td> <td>z: Chip thickness</td> </tr> <tr> <td>$y \leq L$</td> <td>$x \leq 1/8a$</td> <td>$0 < z \leq t$</td> </tr> </table>	y: Chip width	x: Chip length	z: Chip thickness	$y \leq L$	$x \leq 1/8a$	$0 < z \leq t$			
y: Chip width	x: Chip length	z: Chip thickness							
$y \leq L$	$x \leq 1/8a$	$0 < z \leq t$							
<ul style="list-style-type: none"> ⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. ⊙ If the product will be heat sealed by the customer, the alignment mark not be damaged. 									
6.2.3 Substrate protuberance and internal crack.									
 <table border="1" data-bbox="762 1391 1272 1478"> <tr> <td>y: width</td> <td>x: length</td> </tr> <tr> <td>$y \leq 1/3L$</td> <td>$x \leq a$</td> </tr> </table>	y: width	x: length	$y \leq 1/3L$	$x \leq a$					
y: width	x: length								
$y \leq 1/3L$	$x \leq a$								

NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
08	Backlight elements	8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong.	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination. 9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB、COB	10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down.	2.5 2.5 0.65 2.5 2.5 0.65 0.65 2.5
11	Soldering	11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB.	2.5 2.5 2.5 0.65

NO	Item	Criterion	AQL
12	General appearance	12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.	2.5
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on product.	2.5
		12.4 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever.	2.5
		12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color.	2.5
		12.7 Sealant on top of the ITO circuit has not hardened.	0.65
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 LCD pin loose or missing pins.	
		12.10 Product packaging must the same as specified on packaging specification sheet.	0.65
		12.11 Product dimension and structure must conform to product specification sheet.	0.65



Module Number : _____

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1、Panel Specification :

1. Panel Type : Pass NG , _____
2. View Direction : Pass NG , _____
3. Numbers of Dots : Pass NG , _____
4. View Area : Pass NG , _____
5. Active Area : Pass NG , _____
6. Operating Temperature : Pass NG , _____
7. Storage Temperature : Pass NG , _____
8. Others : _____

2、Mechanical Specification :

1. PCB Size : Pass NG , _____
2. Frame Size : Pass NG , _____
3. Material of Frame : Pass NG , _____
4. Connector Position : Pass NG , _____
5. Fix Hole Position : Pass NG , _____
6. Backlight Position : Pass NG , _____
7. Thickness of PCB : Pass NG , _____
8. Height of Frame to PCB : Pass NG , _____
9. Height of Module : Pass NG , _____
10. Others : Pass NG , _____

3、Relative Hole Size :

1. Pitch of Connector : Pass NG , _____
2. Hole size of Connector : Pass NG , _____
3. Mounting Hole size : Pass NG , _____
4. Mounting Hole Type : Pass NG , _____
5. Others : Pass NG , _____

4、Backlight Specification :

1. B/L Type : Pass NG , _____
2. B/L Color : Pass NG , _____
3. B/L Driving Voltage (Reference for LED Type) : Pass NG , _____
4. B/L Driving Current : Pass NG , _____
5. Brightness of B/L : Pass NG , _____
6. B/L Solder Method : Pass NG , _____
7. Others : Pass NG , _____

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Module Number : _____

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5、Electronic Characteristics of Module :

- | | | |
|------------------------------|-------------------------------|-------------------------------------|
| 1. Input Voltage : | <input type="checkbox"/> Pass | <input type="checkbox"/> NG , _____ |
| 2. Supply Current : | <input type="checkbox"/> Pass | <input type="checkbox"/> NG , _____ |
| 3. Driving Voltage for LCD : | <input type="checkbox"/> Pass | <input type="checkbox"/> NG , _____ |
| 4. Contrast for LCD : | <input type="checkbox"/> Pass | <input type="checkbox"/> NG , _____ |
| 5. B/L Driving Method : | <input type="checkbox"/> Pass | <input type="checkbox"/> NG , _____ |
| 6. Negative Voltage Output : | <input type="checkbox"/> Pass | <input type="checkbox"/> NG , _____ |
| 7. Interface Function : | <input type="checkbox"/> Pass | <input type="checkbox"/> NG , _____ |
| 8. LCD Uniformity : | <input type="checkbox"/> Pass | <input type="checkbox"/> NG , _____ |
| 9. ESD test : | <input type="checkbox"/> Pass | <input type="checkbox"/> NG , _____ |
| 10. Others : | <input type="checkbox"/> Pass | <input type="checkbox"/> NG , _____ |

6、Summary :

Sales signature : _____

Customer Signature : _____

Date : / /